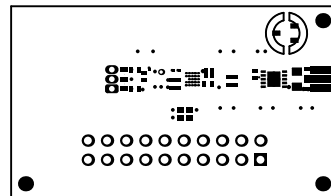
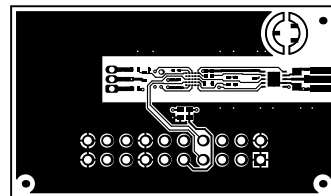


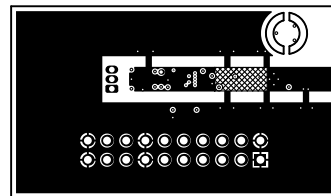
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01239		
PLOT NAME = Top Overlay	GENERATED : 7/24/2017 2:17:46 PM	TEXAS INSTRUMENTS	



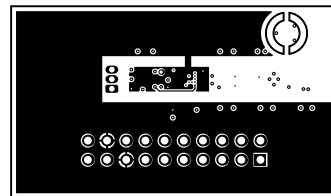
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01239		
PLOT NAME = Top Solder Mask	GENERATED : 7/24/2017 2:17:48 PM	TEXAS INSTRUMENTS	



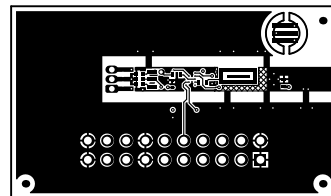
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01239		
PLOT NAME = Top Layer	GENERATED : 7/24/2017 2:17:51 PM	TEXAS INSTRUMENTS	



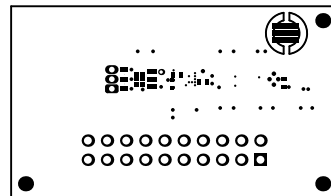
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND Plane	TID #: TIDA-01239		
PLOT NAME = Signal Layer 1	GENERATED : 7/24/2017 2:17:53 PM	TEXAS INSTRUMENTS	



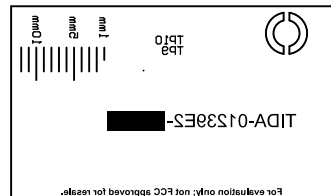
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - VCC Plane	TID #: TIDA-01239		
PLOT NAME = Signal Layer 2	GENERATED : 7/24/2017 2:17:55 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01239		
PLOT NAME = Bottom Layer	GENERATED : 7/24/2017 2:17:58 PM	TEXAS INSTRUMENTS	



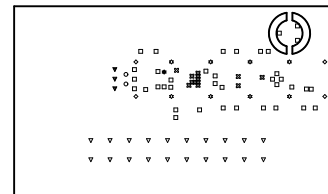
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01239		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/24/2017 2:18:00 PM	TEXAS INSTRUMENTS	



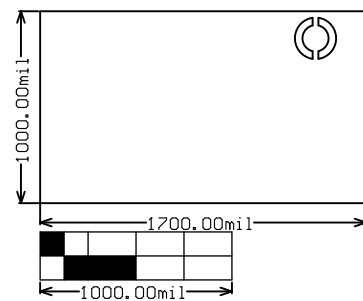
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01239		
PLOT NAME = Bottom Overlay	GENERATED : 7/24/2017 2:18:02 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	2	16.00mil (0.406mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	13	4.00mil (0.102mm)	PTH	Round	Top Layer - Bottom Layer	
□	38	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✱	1	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
▽	3	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
▽	20	40.95mil (1.040mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	39.37mil (1.000mm)	NPTH	Slot	Top Layer - Bottom Layer	
✱	8	39.37mil (1.000mm)	NPTH	Slot	Top Layer - Bottom Layer	
89 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size + Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01239		
PLOT NAME = Drill Drawing	GENERATED : 7/24/2017 2:18:04 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01239	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01239		
PLOT NAME = Board Dimensions	GENERATED : 7/24/2017 2:18:06 PM	TEXAS INSTRUMENTS	

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